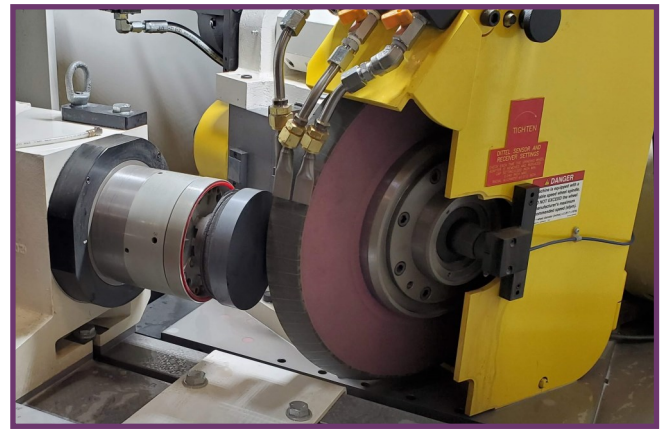
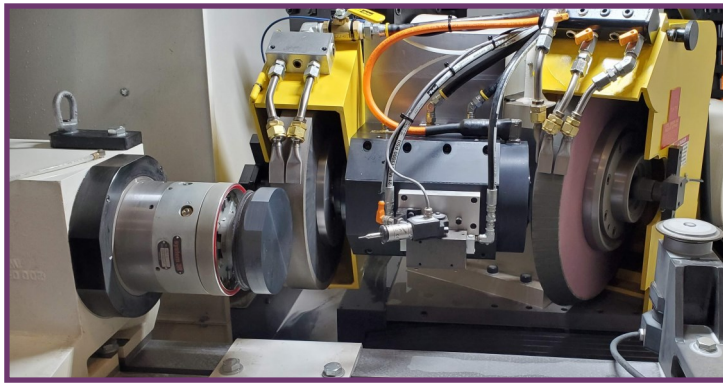


# MIDAS 320A Dual Spindle SiC Grinder

A leader in Silicon Wafer (SiC) technology has once again come to Weldon for solutions to their unique SiC boule (ingot) grinding requirements. In this application, an angular approach grinding wheel is used to grind the OD and end face (dome).



In the same cycle, a sub-spindle with a straight approach wheel is presented to generate (1) or (2) flats to specific C-axis coordinates relative to the grain structure of the crystal. The results are increased productivity, lower production cost, and consistent high quality.



Silicon wafer production cost is greatly reduced with Weldon's unique multi-spindle design allowing OD, Flat, and Face grinding in the same operation. Other processes that can be incorporate into a common platform include formed notch and angled-plane end face grinding.

*System Suppliers: MaxxMagnum system 3R workholding, Setco sub-spindle, Encyclon coolant filtration system, Renishaw probe, Gii electric dresser, Dittel acoustic emissions, Turmoil spindle, linear motor, & coolant chiller, SBS automatic wheel balancer, Heidenhain linear & rotary glass scales, FANUC 32i BT CNC control & X axis linear motor.*



**Weldon Solutions offers a full line of CNC OD, ID, and combination grinders. As a FANUC Robotics integrator, Weldon can also address your machine tending, material removal, material handling, and packaging/palletizing needs.**

## QUALITY, Over and Over Again.

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Contact Weldon today to find out how a new CNC grinder can enhance your manufacturing operation, and increase efficiency and profitability